

F&K Physiktechnik GmbH

Product Catalogue

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1. Transducer Test System TTS-030



- There are two packages for the Transducer Test System TTS-030 available.
- Package 1 is intended for use with fine / thin wire bond machines only.
- Package 2 can be used with heavy wire & die bond machines as well as with fine / thin wire bonders.

Package 1: Transducer Test System TTS-030 for Fine Wire Bonders

Main features and package content:

- max. output power 5 Watts @ 22 Ohms
- voltage and power control modes
- · ODS interface card
- Transducer cable BNC crocodile clips
- RS232 serial cable (Null modem cable)
- USB2.0 to Serial converter
- Carry case for TTS-030 (dimensions approx. 510 mm x 410 mm x 200 mm; Aluminium)
- Power cord (DE plus or UK plug or US plug)
- 230V or 110V

Order number: 100307

Remark:

 Package 1 (Fine wire package) can be upgraded to Package 2 (Heavy wire / Die Bond package) by purchasing an additional upgrade license at a later time.



Package 2: Transducer Test System TTS-030 for Heavy Wire Bonders & Die Bond Machines

Main features and package content:

- max. output power 30 Watts @ 32 Ohms
- voltage and power control modes
- · ODS interface card
- Transducer cable BNC crocodile clips
- RS232 serial cable (Null modem cable)
- USB2.0 to Serial converter
- Carry case for TTS-030 (dimensions approx. 510 mm x 410 mm x 200 mm; Aluminium)
- Power cord (DE plus **or** UK plug **or** US plug)
- 230V or 110V

Order number: 100306

General remark:

- Supply voltage: 230VAC or 110 VAC 50/60 Hz.
- Selected type of power cord plug (DE or UK or US).



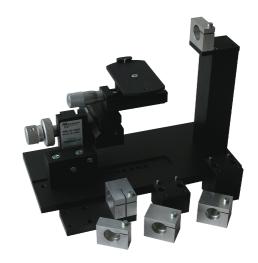
2. Accessories for Transducer Test System TTS-030

Transducer Test Set

Main features and package content:

- · Test Set Base with micro-manipulator
- Transducer clamp 0.5"
- Transducer clamp 0.6"
- Transducer clamp 0.75"
- Transducer clamp 13mm
- Transducer clamp 16mm

Order number: 100322



ODS-TTS Transportation case

Main features and package content:

- Carry case for TTS-030, ODS-20/21 and Transducer Test Set
- external dimensions approx. 620 mm x 420 mm x 210 mm; Aluminium

Order number: 100146



Remark:

• Picture above shows **ODS-TTS Transportation** case with all devices inside. Case contents are not included into order number 100146.

Transducer cable TTS - Crocodile clips





Transducer cable TTS - KnS Ball Bonder

Order number: 100070



Transducer cable TTS - F&K G4

Order number: 100255



Transducer cable TTS - F&K G5





3. Optical Displacement Measurement System ODS-20



- The **ODS-20** comes as a complete package for vibration excursion measurements at the tip of the bonding tool.
- Different sensor head versions available, see package details
- Functionality can be expanded by adding a load cell sensor to evaluate also the bond force unit of a wire bond machine, creating a **2-in-1 system**.

3.1 ODS-20 Standard Package

Package content:

- ODS-20 base device
- Sensor head SK020SL, laser sensor head for vibration measurement only
- ODS-20 CD with software & manuals
- USB2.0 A-B cable
- USB2.0 to Serial converter
- Power supply with plug set (EU, AU, UK & US)
- Storage & carry case



3.2 ODS-20 Shinkawa Package

Package content:

- ODS-20 base device
- Sensor head SK020HL, laser sensor head for vibration measurement only for Shinkawa ball bond machines
- ODS-20 CD with software & manuals
- USB2.0 A-B cable
- USB2.0 to Serial converter
- Power supply with plug set (EU, AU, UK & US)
- Storage & carry case

Order number: 100398

3.3 Available sensor head options:

Sensor head SK020SB

Separate sensor head for bond force measurements.

Order number: 100444



Sensor head SK020SF

Combined sensor head, load cell integrated into laser head.

Order number: 100188



Remarks:

• 2-in-1 Solution:

ODS-20 Standard Package can be ordered together with additional sensor head SK020SB, so it will be shipped with two sensor heads (SK020SL & SK020SB). Recommended configuration for customer requiring not only vibration excursion measurements, but also bond force measurement.

• Standard load cell for bond forces up to 2 kg (20N). Other force ranges on request, please ask.



4. Optical Displacement Measurement System ODS-21



- There are two packages for the Optical Displacement Measurement System ODS-21 available.
- Standard Package is intended for use with fine / thin wire bond machines only.
- **BFS Package** is also a **2-in1 soultion** and to measure not only the vibration excursion on K&S ball bonders but also the bond force.

Package 1: ODS-21 Standard Package for K&S bonders

Main features and package content:

- ODS-21 with vibration excursion measurement only, seamless replacement of the K&S USG PORTABILITY CALIBRATION KIT
- ODS-21 base device
- Sensor head SK021KL, laser sensor head for vibration measurement only
- Shim block
- PC-Host-SW (CD)
- USB 2.0 A-B cable
- RS232 cable DSUB9m/f crossed
- Power supply with plug set (EU, AU, UK & US)
- Storage & carry case



Package 2: ODS-21 BFS Package (with additional bond force sensor for K&S bonders)

Main features and package content:

- **ODS-21** with vibration excursion measurement and bond force measurement, extended replacement of the *K&S USG PORTABILITY CALIBRATION KIT*
- ODS-21 base device
- Sensor head SK021KL, laser sensor head for vibration measurement only
- Sensor head SK021KD, additional sensor head for bond force measurements
- Shim block
- PC-Host-SW (CD)
- USB 2.0 A-B cable
- RS232 cable DSUB9m/f crossed
- Power supply with plug set (EU, AU, UK & US)
- Storage & carry case

Order number: 100316

Remark:

Standard load cell for bond forces up to 2 kg (20N).
 Other force ranges on request, please ask.



5. Bond Force Calibration System BFS-20



- The **BFS-20** comes as a complete package for calibrating the bond force unit of F&K Delvotec wire bonders.
- It can be used also on other wire bonder brands to evaluate the function of the bond force unit.

Package content:

- BFS-20 base device
- Sensor head SK020SB, sensor head for force measurement only
- BFS-20 CD with software & manuals
- RS232 serial cable (Null modem cable) for communication with F&K bonder
- USB 2.0 A-B cable
- Power supply with plug set (EU, AU, UK & US)
- Storage & carry case

Order number: 100388

Remark:

• Standard load cell for bond forces up to 2 kg (20N). Other force ranges on request, please ask.



6. Ultrasonic Generators

- There is the UUG-050 family of fully digital ultrasonic generators for wire and (flip-chip) die bonding available.
- These generators usually come with housing and power supply. However for very price sensitive markets the UUG-050 standard model and the UUG-050-B model are also available as board level versions.
- Also the other generator models are fully digital generators.

UUG-050

Order number: 100167



Remark:

Standard model for fine/thin wire bonding (ball & wedge bonder).

UUG-050-B

Order number: 100175



Remark:

- Increased power compared to standard model
- · Recommended for Ultrasonic Flip-Chip die bonders for low pin counts

UUG-050 Board

Order number: 100363

Remark:

 Standard model as board level version. Recommended for fine wire bonder (ball & wedge bonder) for machine integration.



UUG-050-B Board

Order number: 100362

Remark:

• Increased power version as board level generator. Recommended for Ultrasonic Flip-Chip die bonders for low pin counts for machine integration.



UUG-130

Order number: 100456



Remark:

 Recommended for Ultrasonic Flip-Chip die bonders for small (low) and medium pin counts & wire bonders

UUG-140

Order number: 100487



Remark:

 Recommended for Ultrasonic Flip-Chip die bonders for medium pin counts & heavy wire bonders

UUG-050-X

Order number: 100323

Diplot Utranspare Congresses UUG-050-X

Remark:

 Recommended for U/S flip chip die bonders with high bond force / high pin counts & heavy wire/heavy ribbon (HARB) bonders

DUG-100

Order number: 100418

Remark:

Recommended for use with high power transducers PTP series.



Available options:

PC-Host Software for UUG-050 family

Order number: 100278

PC-Host Software for UUG-130 (digital delivery)

Order number: 900001

PC-Host Software for UUG-140 (digital delivery)

Order number: 900002

General Remarks:

• All UUG models are fully digital systems.

- Communication protocols for UUG-050 family and UUG-1xx for seamless machine integration available on request.
- Customized version on request.



7. Ultrasonic Transducers

Fine/Thin wire wedge-wedge transducer

•	FK065-D1	65 kHz	Order No.: 100115
•	FK100C-0	100 kHz	Order No.: 100085
•	FK100C-3	100 kHz	Order No.: 100086
•	FK120N	120 kHz	Order No.: 100087
•	FK140R-1	140 kHz	Order No.: 100090

PTW100A0 100 kHz Order No.: N.A. - please ask (low cost version)

Fine/Thin wire ball-wedge transducer

•	FK066G	66 kHz	Order No.: 100355
•	FK067M	67 kHz	Order No.: 100501
•	FK067X	67 kHz	Order No.: 100125
•	FK100F-2	100 kHz	Order No.: 100089
•	FK120S-2	120 kHz	Order No.: 100092
•	FK140L	140 kHz	Order No.: N.A.
•	FK145P	145 kHz	Order No.: 100196

• **PTB065A0** 65 kHz Order No.: **100449** (low cost version)

Heavy Wire / Die-bond transducer

•	FK040U	38 kHz	Order No.: 100091
•	FK054A	57 kHz	Order No.: 100088
•	FK058HR	58 kHz	Order No.: 100258
•	FK090Z-1	88 kHz	Order No.: 100280
•	FK120K	120 kHz	Order No.: 100185
•	FK120KD	120 kHz	Order No.: N.A.

• **PTH060A0** 58 kHz Order No.: **100485** (low cost version)

TAB transducer

FK065TAB 65 kHz Order No.: N.A.







High power transducer

PTP030A0 30 kHz Order No.: 100469
 PTP040A0 44 kHz Order No.: 100470



Remark:

o Other frequencies or models on request.



Contact

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